

Page 2 **BLOCK DIAGRAM**

Page 3 **SELF POWER + REGULATOR +FSD +LDO**

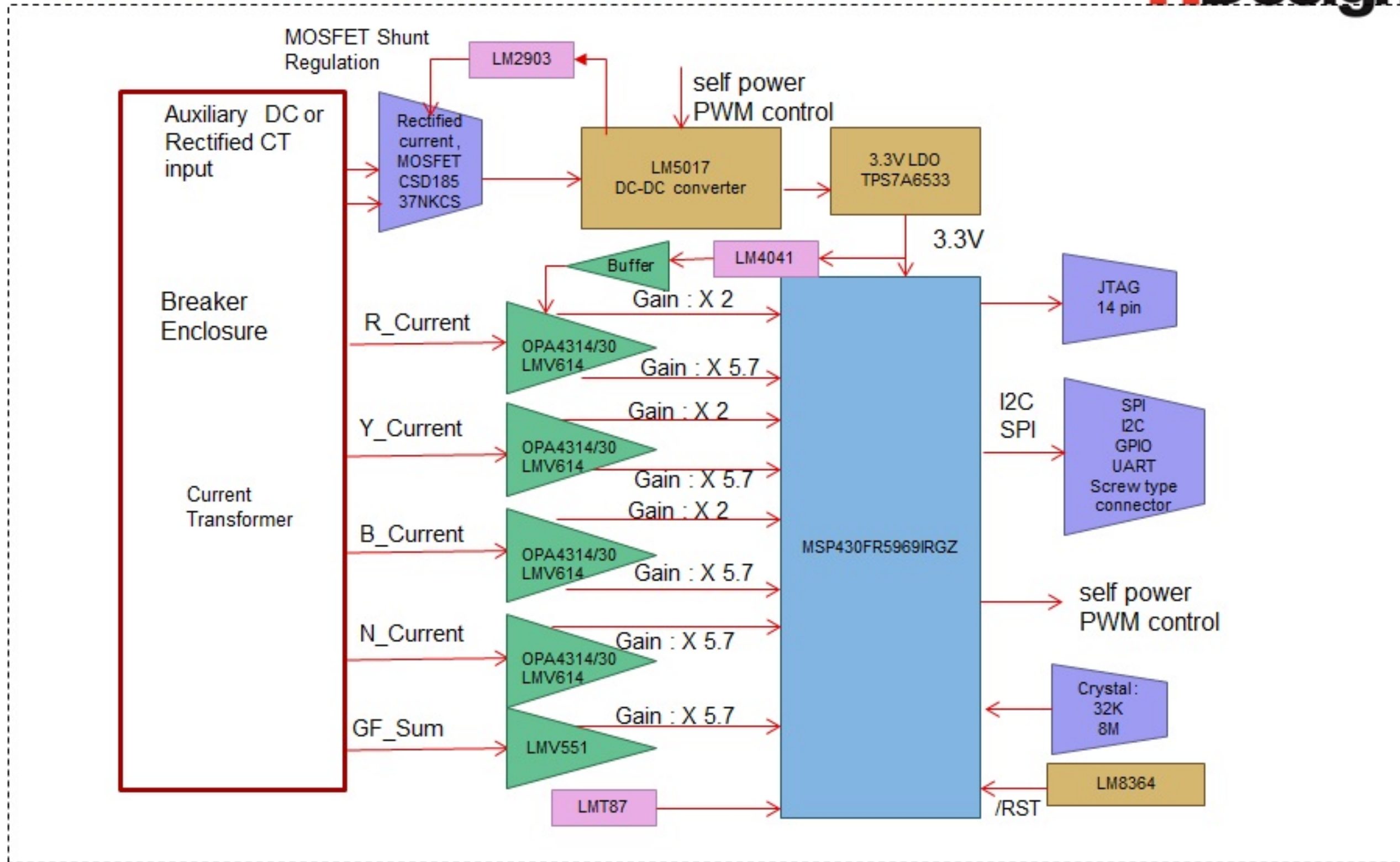
Page 4 **ANALOG FRONT END OPAMP +TEMP SENSOR**

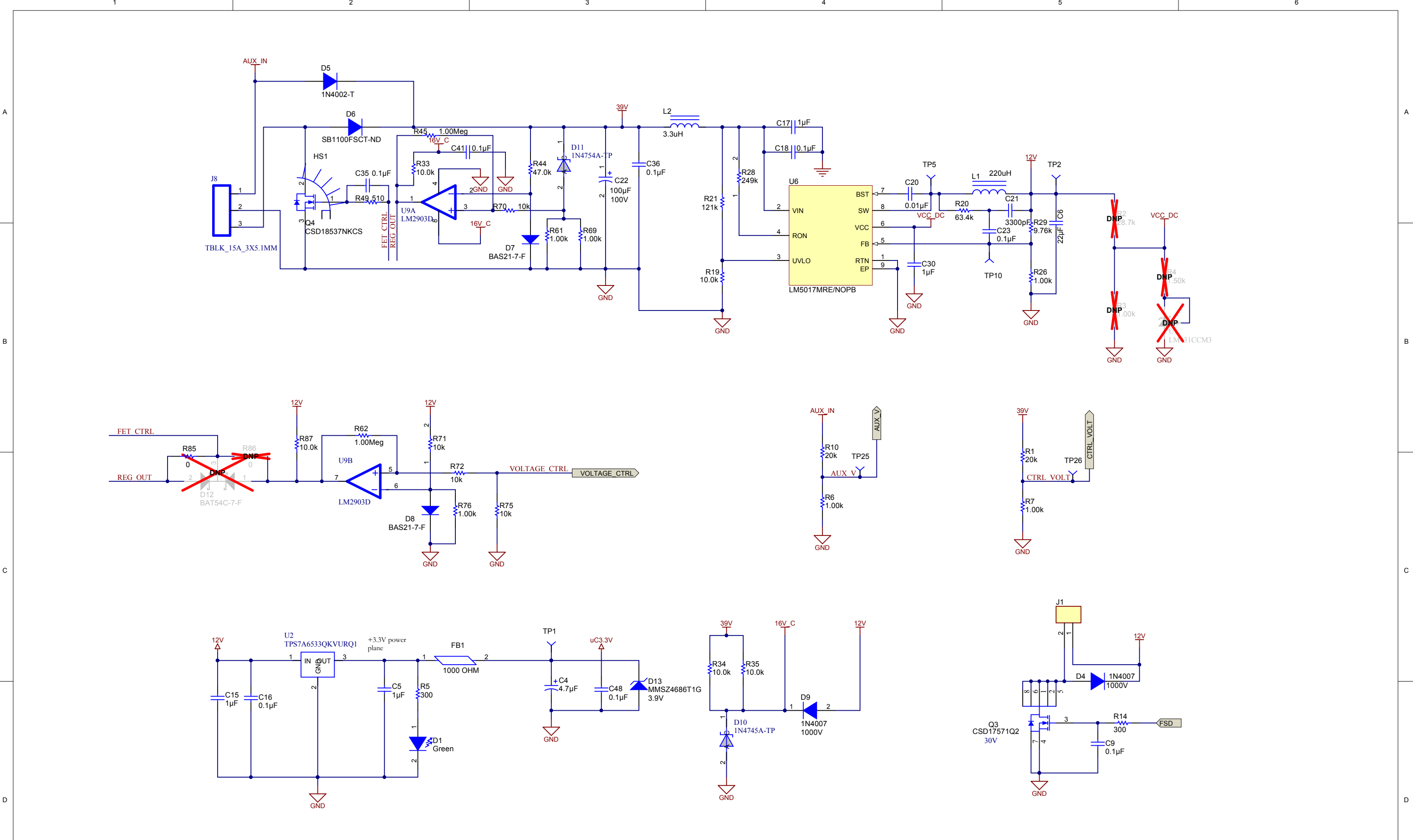
Page 5 **MCU + LED INDICATION**

Page 6 **HARDWARE - MISCELLANEOUS**

Revision History	
Revision	Notes

Signal Processing Subsystem for ACB/MCCB





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A

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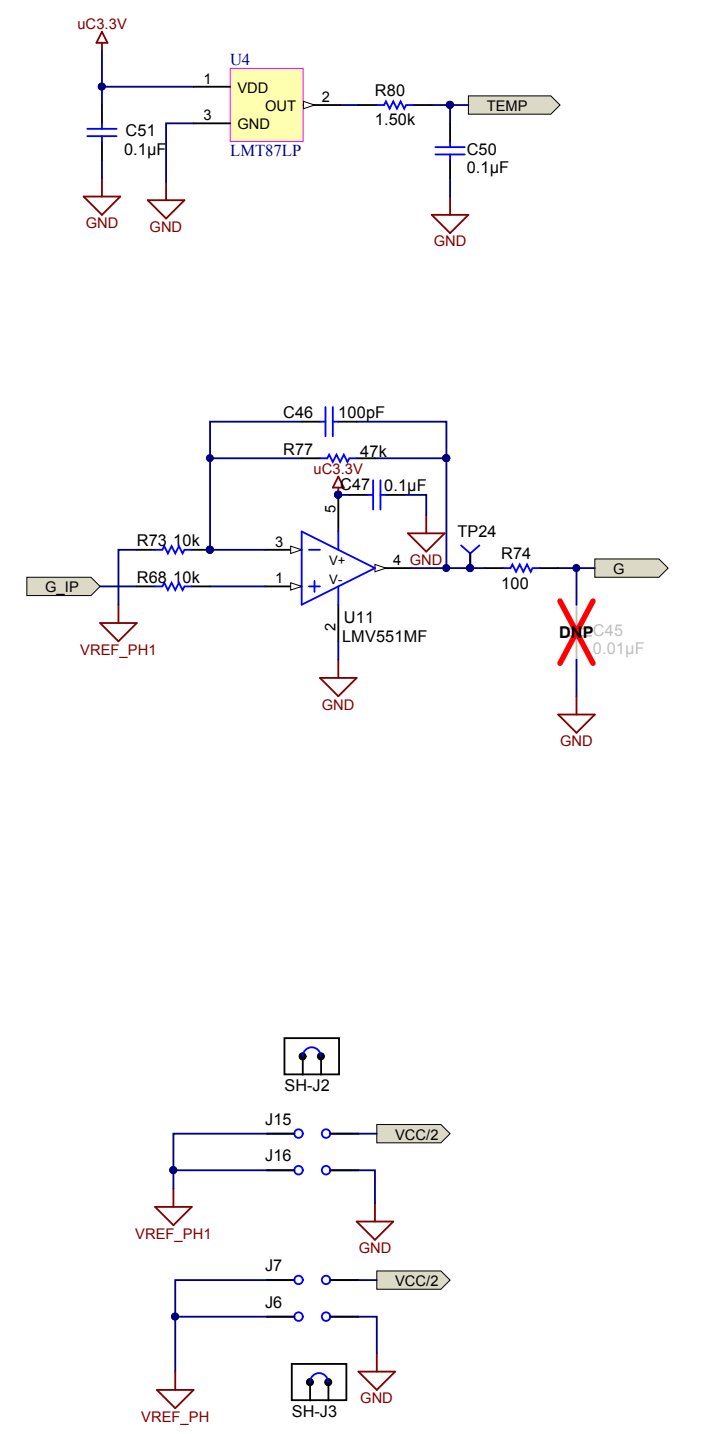
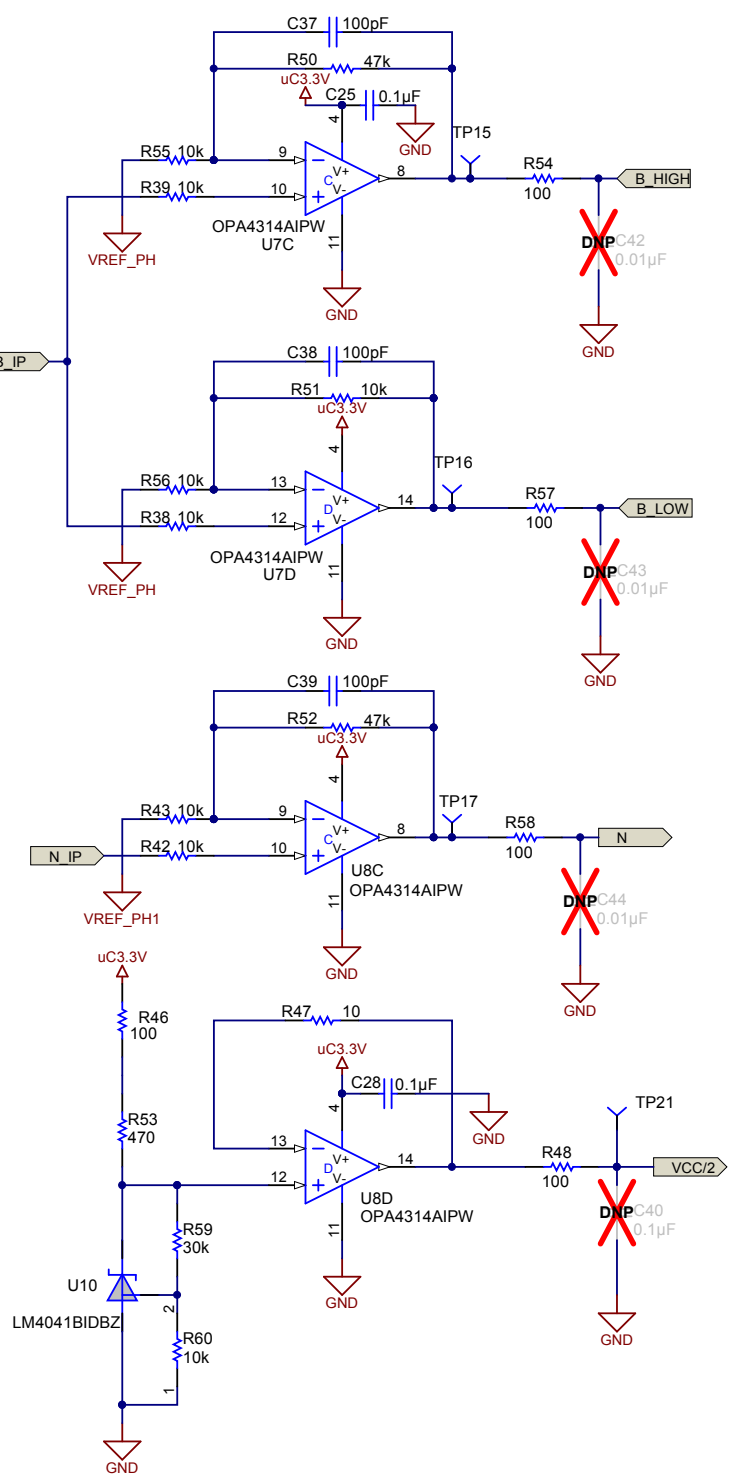
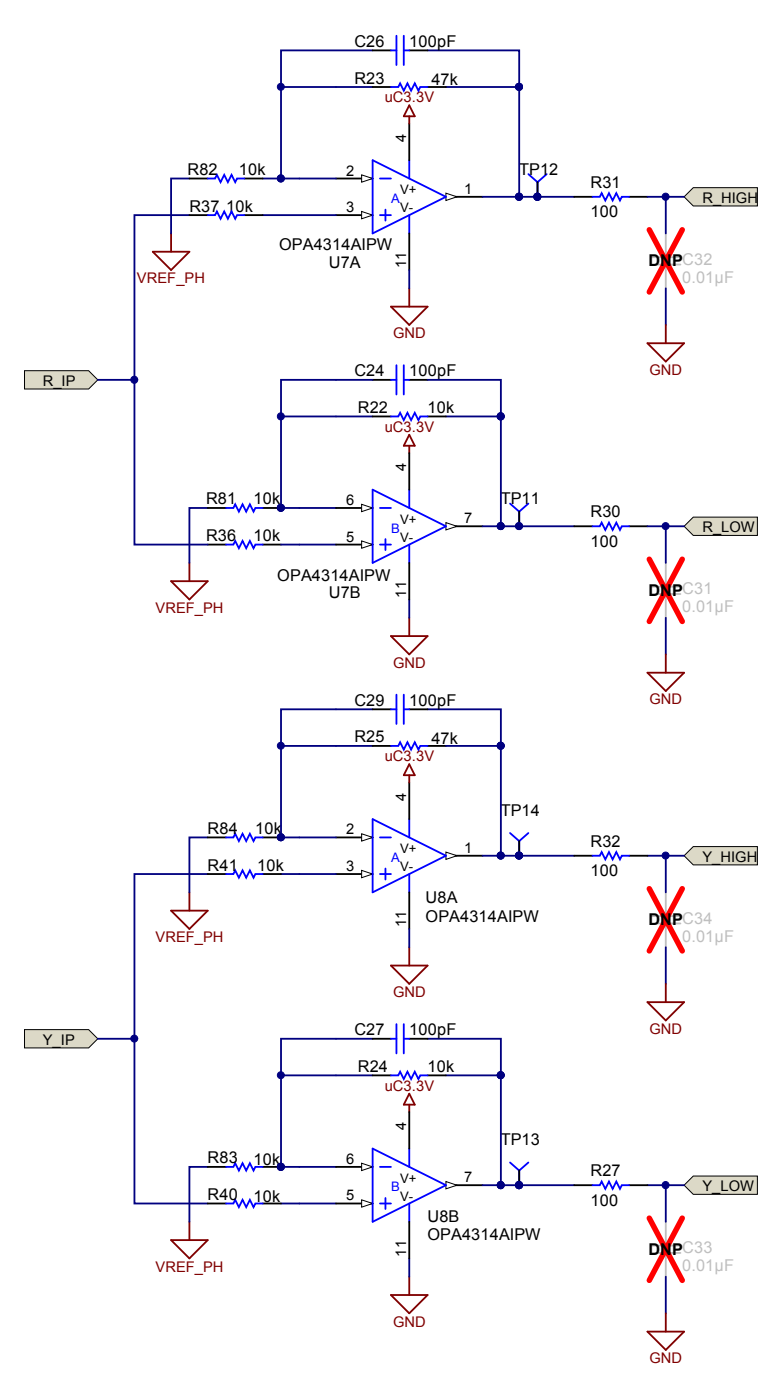
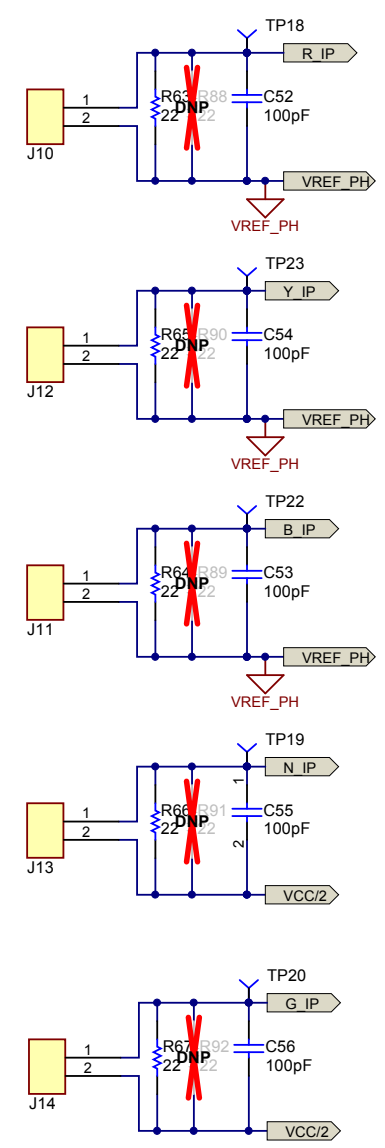
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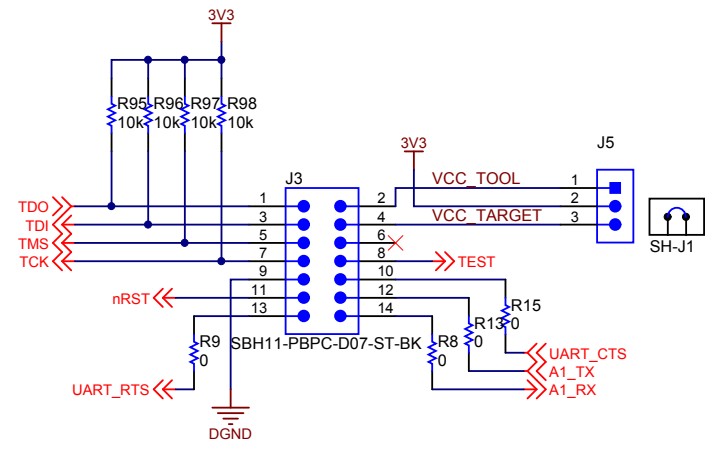
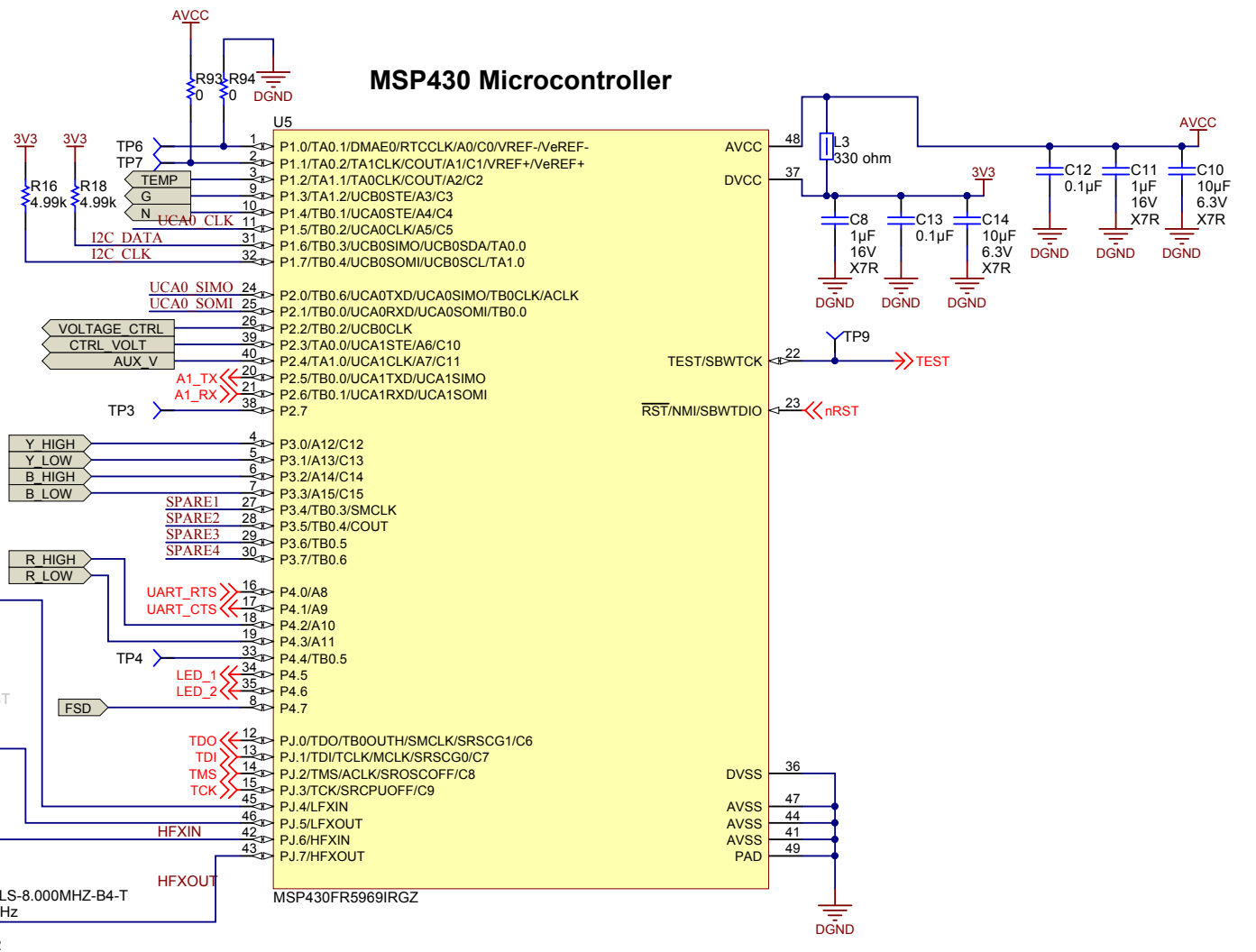
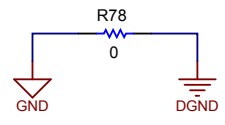
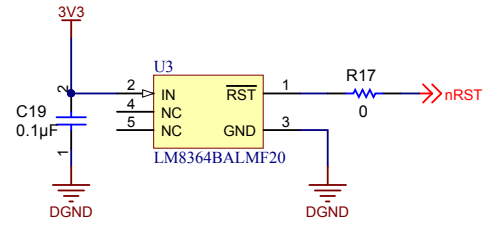
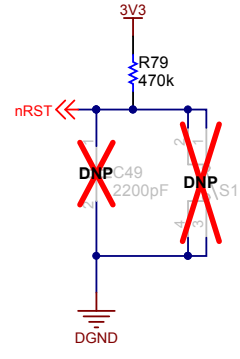
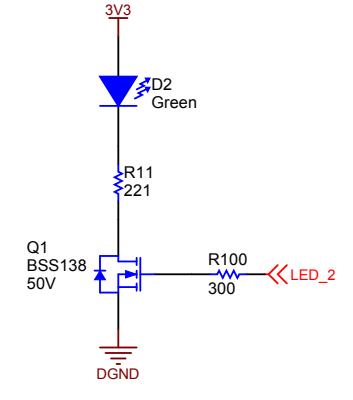
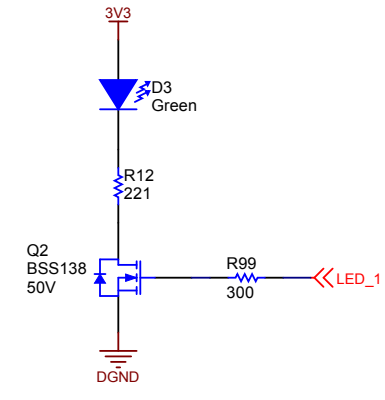
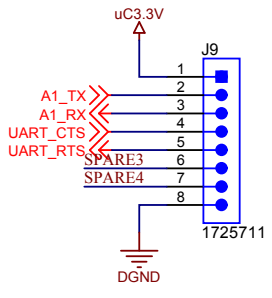
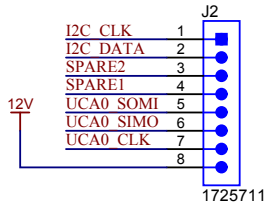
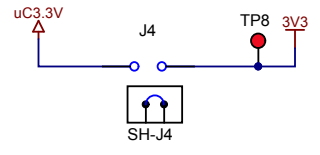
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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

FID3 FID2 FID1 FID6 FID5 FID4

PCB Number: TIDA-00498
PCB Rev: E2

PCB
LOGO
Texas Instruments

Label Table

Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label

Size: 0.65" x 0.20 "

ZZ2
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Designed for: Public Release		Mod. Date: 6/2/2015	
Project Title: TIDA-00498 OPAMP BASED MCCB FRONTEND			
Number: TIDA-00498		Rev: E2	
SVN Rev: Not in version control		Assembly Variant: 001	
Drawn By:		File: Pg6 Hardware.SchDoc	
Engineer: Enter name of project lead		Contact: http://www.ti.com/support	
Sheet Title:		Sheet: 6 of 6	
		Size: B	
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